

TSMC-00-523

October 26, 2001

2812
#3/205
J. J. J.
10/2/01

To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
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Subject:

Serial No. 09/945,432 09/04/01

Chung Liu, Yuan-Lung Liu,
Ruey-Yun Shiue

NOVEL MESH PAD STRUCTURE TO
ELIMINATE IMD CRACK ON PAD

Grp. Art Unit: 2812

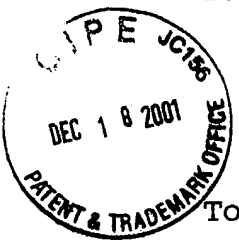
INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

U.S. Patent 6,002,179 to Chan et al., "Bonding Pad
Structure for Integrated Circuit (I)," teaches a bonding pad
structure with increased peeling resistance.

U.S. Patent 5,731,243 to Peng et al., "Method of Cleaning
Residue on a Semiconductor Wafer Bonding Pad," discloses a
cleaning method to ensure contamination free bonding.



The following two U.S. Patents disclose bonding pad structures that resist bond pad peeling:

- 1) U.S. Patent 6,025,277 to Chen et al., "Method and Structure for Preventing Bonding Pad Peel Back."
- 2) U.S. Patent 5,707,894 to Hsiao, "Bonding Pad Structure and Method Thereof."

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761